

bq3055EVM SBS 1.1 Compliant Advanced Gas Gauge Battery Management Solution EVM

The bq3055EVM is a complete evaluation system for the bq3055/bq29440 battery management system. This system includes one bq3055/bq29440 circuit module, a current sense resistor, two thermistors, and a link to Windows®-based PC software.

The circuit module includes one bq3055 IC, one bq29440 IC, and all other onboard components necessary to monitor and predict capacity, perform cell balancing, monitor critical parameters, protect the cells from overcharge, overdischarge, short circuit, and overcurrent in 2-series, 3-series, or 4-series cell Li-ion or Li-polymer battery packs. The circuit module connects directly across the cells in a battery.

With the EV2300 or EV2400 interface board and software, users can read the bq3055 data registers, program the chipset for different pack configurations, log cycling data for further evaluation, and evaluate the overall functionality of the bq3055/bq29440 solution under different charge and discharge conditions.

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1 Features

- Complete evaluation system for the bq3055 SBS 1.1-compliant advanced gas gauge, bq3055 and bq29440 independent overvoltage protection integrated circuit (IC)
- Populated circuit module for quick setup
- · Link to software that allows data logging for system analysis

1.1 Kit Contents

- bq3055/bq29440 circuit module
- · Set of support documentation

1.2 Ordering Information

Table 1. Ordering Information

| EVM PART NUMBER | CHEMISTRY | CONFIGURATION | CAPACITY |
|-----------------|-----------|---|----------|
| bq3055EVM-001 | Li-ion | 2-series, 3-series, or 4-series cell | Any |

2 bq3055 Device-Based Circuit Module

The bq3055/bq29440-based circuit module is a complete and compact example solution of a bq3055 circuit for battery management and protection of Li-ion or Li-polymer packs. The circuit module incorporates a bq3055 battery monitor IC, bq29440 independent overvoltage protection IC, and all other components necessary to accurately predict the capacity of 2-series, 3-series, or 4-series cells.

2.1 Circuit Module Connections

Contacts on the circuit module provide the following connections:

- Direct connection to the cells: 1N (BAT-), 1P, 2P, 3P, 4P (BAT+)
- To the serial communications port (SMBC, SMBD, VSS)
- The system load and charger connect across PACK+ and PACK-
- To the system present pin (SYS PRES)



2.2 Pin Descriptions

| PIN NAME | DESCRIPTION |
|----------|--|
| 1N | -ve connection of first (bottom) cell |
| 1P | +ve connection of first (bottom) cell |
| 2P | +ve connection of second cell |
| 3P | +ve connection of third cell |
| 4P | +ve connection of fourth (top) cell |
| SMBC | Serial communication port clock |
| SMBD | Serial communication data port |
| VSS | Pack negative terminal |
| PACK- | Pack negative terminal |
| SYS PRES | System present pin (if low, system is present) |
| PACK+ | Pack positive terminal |

3 **bq3055 Circuit Module Schematic**

This section contains information on the schematic for the bg3055/bg29440 implementation.

3.1 Schematic

The schematic follows the bill of materials in this user's guide.

3.2 Choosing Particular Precharge Mode

The bq3055 contains an internal precharge FET; however, the default firmware configuration uses the Charge FET for precharge. To evaluate the internal precharge FET, change the least two significant bits in DF:Configuration:Charging Configuration to be 0.0. See the bg3055 Technical Reference Manual (SLUU440) for additional information.

3.3 **Testing Fuse-Blowing Circuit**

To prevent the loss of board functionality during the fuse-blowing test, the actual chemical fuse is not provided in the circuit. FET Q1 drives TP8 low if a fuse-blow condition occurs; monitoring TP8 can be used to test this condition.

4 Circuit Module Physical Layouts and Bill of Materials

This section contains the board layout, bill of materials, and assembly drawings for the bq3055/bq29440 circuit module.

4.1 **Board Layout**

SLUU824-December 2011

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This section shows the dimensions, PCB layers, and assembly drawing for the bq3055 module.

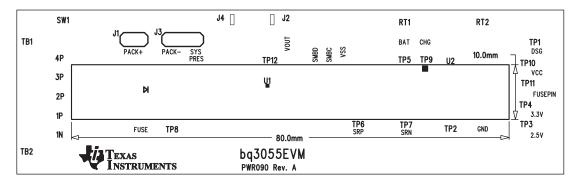


Figure 1. bq3055EVM-001 Layout (Silk Screen)



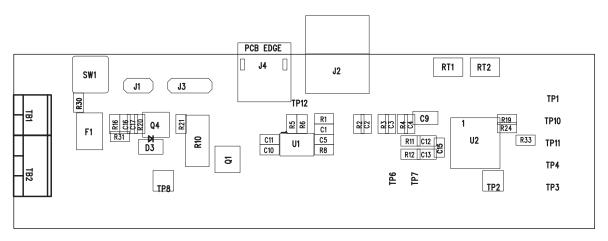


Figure 2. Top Assembly

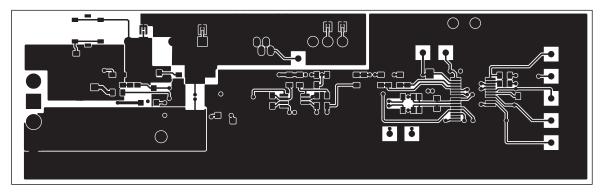


Figure 3. Top Layer

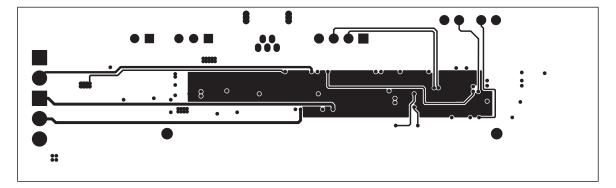


Figure 4. Inner Layer 1



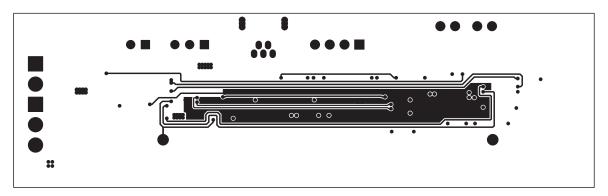


Figure 5. Inner Layer 2

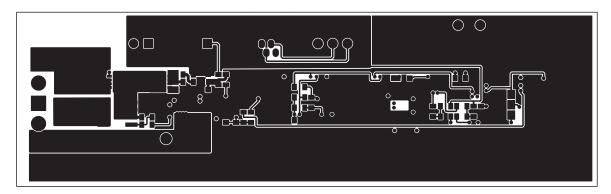


Figure 6. Bottom Layer

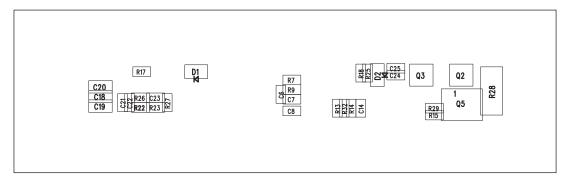


Figure 7. Bottom Assembly



4.2 Bill of Materials

Table 2. Bill of Materials

| Count | Reference Design | Value | Description | Size | Part Number | Manufacturer |
|-------|---|------------|---|-------------------------|---------------------|--------------|
| 18 | C1, C2, C3, C4, C5, C6, C7, C8, C11, C12, C13, C14, C15, C16, C17, C21, C24, C25 | 0.1 µF | Capacitor, Ceramic, 50 V, X7R, 20% | 0603 | Std | Std |
| 1 | C10 | 0.22 μF | Capacitor, Ceramic, 25 V, X7R, 20% | 0603 | Std | Std |
| 4 | C20, C9, C18, C19 | 1.0 µF | Capacitor, Ceramic, 25 V, X7R, 20% | 0805 | Std | Std |
| 2 | C22, C23 | 0.1 nF | Capacitor, Ceramic, 50 V, X7R, 20% | 0603 | Std | Std |
| 2 | D1, D3 | 1SS355 | Diode, Switching, 90 V, 225 mA Ifm, High speed | SOD-323 | 1SS355-17 | Rohm |
| 1 | D2 | MM3Z5V6C | Diode, Zener, 5.6 V, 200 mw | SOD323 | MM3Z5V6C | Fairchild |
| 1 | J1 | PEC02SAAN | Header, Male 2-pin, 100mil spacing | 0.100 inch x 2 | PEC02SAAN | Sullins |
| 1 | J2 | 22-05-3041 | Header, Friction Lock Ass'y, 4-pin Right Angle | 0.400 x 0.500 | 22-05-3041 | Molex |
| 1 | J3 | PEC03SAAN | Header, Male 3-pin, 100 mil spacing, (36-pin strip) | 0.100 inch x 3 | PEC03SAAN | Sullins |
| 1 | J4 | 56579-0519 | Connector, USB, Mini AB 5-pins | 0.354 X 0.307 Inches | 56579-0519 | Molex |
| 1 | Q1 | FDN339AN | MOSFET, N-ch, 20 V, 3A, 0.05 Ω | SOT23 | FDN339AN | Fairchild |
| 2 | Q2, Q3 | Si7114DN | MOSFET, Fast Switching, NChan, 30 V, 18.3 A, 7.5 mΩ | PWRPAK 1212 | Si7114DN-T1-E3 | Vishay |
| 1 | Q4 | 2N7002K | MOSFET, Nch, 60 V, 300 mA, 2 Ω | SOT23 | 2N7002K-T1-E3 | Vishay |
| 1 | Q5 | FDS4435BZ | MOSFET, Pch, -30 V, -8.8 A, 20 mΩ | SO8 | FDS4435BZ | Fairchild |
| 9 | R1, R2, R3, R4, R11, R12, R18, R26, R27 | 100 | Resistor, Chip, 1/16-W, 5% | 0603 | Std | Std |
| 1 | R10 | 0.01 | Resistor, Chip, 1-W, 1%, 75ppm | 2512 | WSL2512R0100F EA | Vishay |
| 2 | R13, R32 | 50K | Resistor, Chip, 1/16-W, 5% | 0603 | Std | Std |
| 1 | R14 | 220K | Resistor, Chip, 1/16-W, 5% | 0603 | Std | Std |
| 3 | R15, R17, R19 | 5.1K | Resistor, Chip, 1/16-W, 5% | 0603 | Std | Std |
| 2 | R16, R20 | 3M | Resistor, Chip, 1/16-W, 5% | 0603 | Std | Std |
| 4 | R21, R24, R30, R33 | 10K | Resistor, Chip, 1/16-W, 5% | 0603 | Std | Std |
| 2 | R22, R23 | 200 | Resistor, Chip, 1/16-W, 5% | 0603 | Std | Std |
| 6 | R25, R5, R6, R7, R8, R9 | 1K | Resistor, Chip, 1/16-W, 5% | 0603 | Std | Std |



Table 2. Bill of Materials (continued)

| Count | Reference Design | Value | Description | Size | Part Number | Manufacturer |
|--|--|------------|--|----------------------------|--------------------------|--------------------------------|
| 1 | R28 | 300 | Resistor, Chip, 1W, 5% | 2512 | Std | Std |
| 1 | R29 | 1M | Resistor, Chip, 1/16W, 5% | 0603 | Std | Std |
| 1 | R31 | 0 | Resistor, Chip, 1/16-W, 5% | 0603 | Std | Std |
| 2 | RT1, RT2 | 10K | Thermistor | 0.095 X 0.150 | CH25-3H103 or 103AT-2 | Mitsubishi Material or Semitec |
| 1 | SW1 | EVQ-PLHA15 | Switch, Push button, Momentary, 1P1T, 50-mA, 12-V | 0.200 x 0.200 inch | EVQ-PLHA15 | Panasonic |
| 1 | TB1 | ED1514 | Terminal Block, 2-pin, 6-A, 3.5mm | 0.27 x 0.25 | ED555/2DS | OST |
| 1 | TB2 | ED1515 | Terminal Block, 3-pin, 6-A, 3.5mm | 0.41 x 0.25 | ED555/3DS | OST |
| 12 | TP10, TP11, TP1, TP12, TP2, TP3, TP4, TP5, TP6, TP7, TP8, TP9 | | Test Point, White, Thru Hole Color Keyed | 0.100 x 0.100 inch | 5002 | Keystone |
| 1 | U1 | BQ29412DCT | IC, Voltage Protection for 2, 3, 4 Cell Lion , 2nd Protection, 4.45 v OVP | SSOP-08 | BQ29412DCT | TI |
| 1 | U2 | BQ3055DBT | IC, CoolRISC Programmable Battery Manager | TSSOP-38 (DBT) | BQ3055DBT | TI |
| 1 | _ | | PCB | | PWR090 | Std |
| Notes: 1. These assemblies are ESD sensitive, ESD precautions shall be observed. 2. These assemblies must be clean and free from flux and all contaminants. Use of no 3. These assemblies must comply with workmanship standards IPC-A-610 Class 2. 4. Ref designators marked with an asterisk (***') cannot be substituted. All other components can be substituted with equivalent MFG's components. 5. Make one SMBus connector wire assembly for each assembly produced, from J4 m terminals. Wire colors for Pin numbers are listed below. The wire assembly shall have Red - Pin # 4 (Signal USB_5V) Brown - Pin # 3 (Signal SDA) White - Pin # 2 (Signal SCL) | | | | s 2. n J4 mate, 4–24 Av | vg wires and Crimp | |

White - Pin # 2 (Signal SCL)
Black - Pin # 1 (GND)



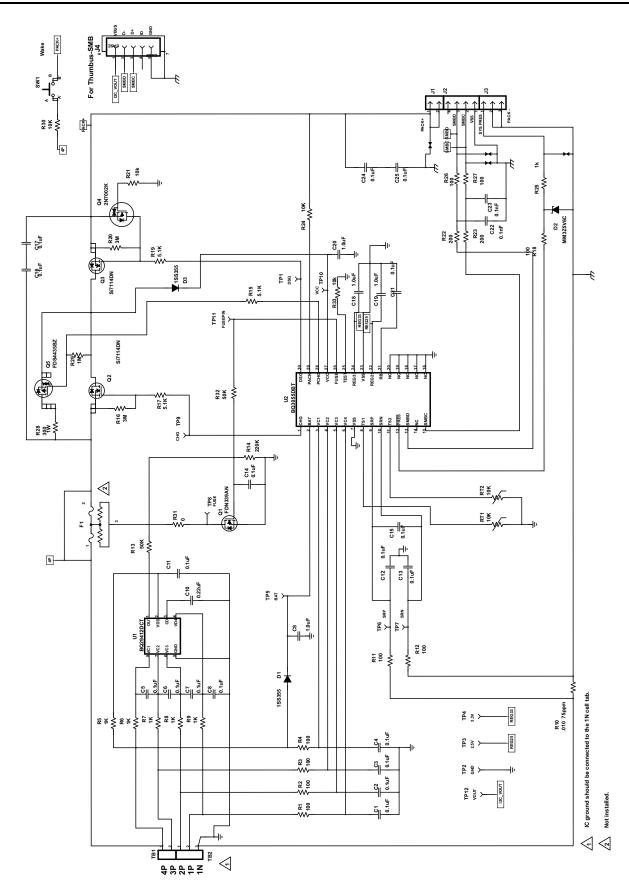


Figure 8. Schematic



4.3 bq3055/bq29440 Circuit Module Performance Specification Summary

This section summarizes the performance specifications of the bg3055/bg29440 circuit module.

Table 3. Performance Specification Summary

| Specification | Min | Тур | Max | Units |
|------------------------------|-----|-----|-----|-------|
| Input voltage Pack+ to Pack- | 5 | 15 | 25 | V |
| Charge and discharge current | 0 | 2 | 7 | Α |

5 EVM Hardware and Software Setup

This section describes how to install the bq3055EVM-001 PC software, and how to connect the different components of the EVM.

5.1 System Requirements

The bq3055EVSW requires Windows 2000, XP, Vista, or 7.

5.2 Software Installation

NOTE: To get the latest software archive, contact the Texas Instruments field representative assigned to work with this device.

To install the bg3055EVSW software, do the following:

- 1. Save the archive to a temporary directory.
- Double-click on the executable filename, and follow the installer instructions to complete the bq3055 EVSW installation.

If the EV2300 or EV2400 was not previously installed: After bq3055 EVSW installation, a TI USB DRIVER INSTALLER pops up. Click **Yes** for the agreement message and follow its instructions.

3. Plug the EV2300 or EV2400 into a USB port.

6 Troubleshooting Unexpected Dialog Boxes

Users downloading the files must be logged in as the administrator, or must have privileges to install new programs.

The driver is not signed, so the administrator must allow installation of unsigned drivers in the operating system policy.

7 Hardware Connection

The bq3055EVM-001 comprises two hardware components: the bq3055/bq29440 circuit module and the EV2300 or EV2400 PC interface box.

7.1 Connecting the bg3055/bg29440 Circuit Module to a Battery Pack

Figure 9 shows how to connect the bq3055/bq29440 circuit module to the cells and system load/charger.

The cells must be connected in the following order:

- 1. 4-Cell Pack: 1N (BAT-), 1P, 2P, 3P, then 4P (see Section 2.2 for definitions).
- 2. 3-Cell Pack: 1N (BAT-), 1P, 2P, and then connect 4P and 3P together.
- 3. 2-Cell Pack: 1N (BAT-), 1P, and then connect 4P, 3P, and 2P together.

To start charge or discharge test, connect SYS PRES pin to Pack– pin to set SYS PRES state. To test sleep mode, disconnect the SYS PRES pin.



Hardware Connection www.ti.com

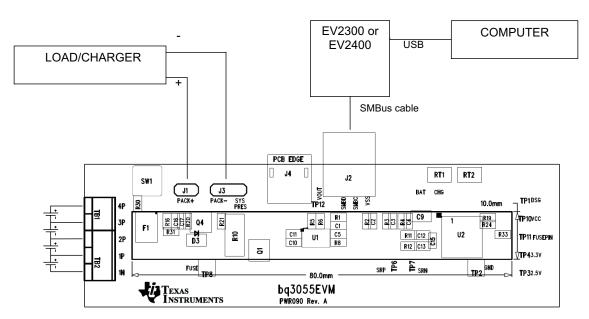


Figure 9. bq3055 Circuit Module Connection to Cells and System Load/Charger

7.2 PC Interface Connection

To configure the hardware to interface to the PC, do the following:

1. Connect the bq3055 device-based smart battery to the EV2300 or EV2400 using the provided cable or the connections shown in Table 4.

Table 4. Circuit Module to EV2300 or EV2400 Connections

| bq3055 Device-Based Battery | EV2300 or EV2400 |
|-----------------------------|------------------|
| SMBD | SMBD |
| SMBC | SMBC |
| VSS | GND |

2. Connect the PC USB cable to the EV2300 or EV2400 and the PC USB port.

The bq3055EVM-001 is now set up for operation.



Operation www.ti.com

8 Operation

This section details the operation of the bq3055 EVSW software.

NOTE: The EV2300 or EV2400 driver does not support Windows Sleep or Hibernate states. If communicating with the EV2300 or EV2400 or the EVM presents a problem, unplug the USB cable and then plug it back in. If the problem continues, determine if the EVM is in Shutdown mode. The bq3055 can be awakened by momentarily pressing SW1 if cell voltage is present.

8.1 Starting the Program

With the EV2300 or EV2400 and the bq3055EVM connected to the computer, run bq3055 EVSW from the Desktop Icon or Start | All Programs | Texas Instruments | bg Evaluation Software menu sequence. The SBS Data Screen appears. Data begins to appear once the Refresh (single time scan) button is clicked, or when the Keep Scanning check box is checked. To disable the scan feature, deselect Keep Scanning.

The continuous scanning period can be set via the Options and Set Scan Interval menu selections. The range for this interval is 0 ms to 65535 ms. Only items that are selected for scanning are scanned within this period.

The bq3055 EVSW provides a logging function that logs the values that were last scanned by EVSW. To enable this function, click the Start Logging button; this causes the Keep Scanning button to be selected. When logging is Stopped, the Keep Scanning button is still selected and has to be manually unchecked.

The logging interval is specified under the *Options* menu with the maximum value of 65535 ms. The *Log* interval cannot be smaller than the scan interval because this results in the same value being logged at least twice.



Operation www.ti.com

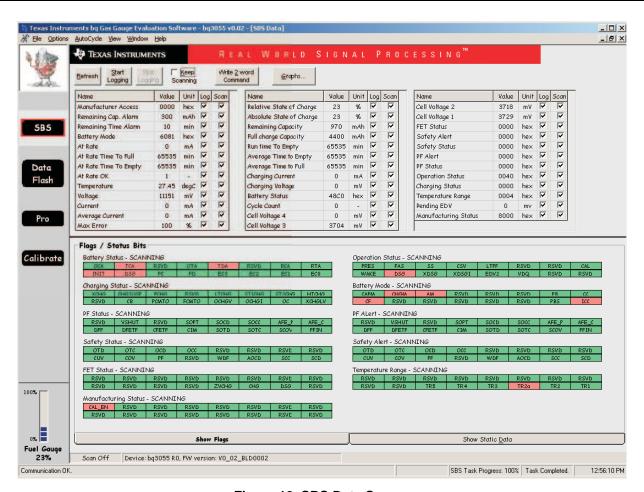


Figure 10. SBS Data Screen

This screen shows the SBS data set along with additional ManufacturersAccess() command information, such as individual cell measurements. Additional Flag and Static data can be viewed by selecting the appropriate tab at the bottom of the SBS screen.

Data such as SBS.ManufacturerName() is static and does not change. This data is viewed separately using the *Static Data* tab at the bottom of the screen.

Dragging the splitter bar (line that separates the Flags/Static data from SBS values) changes the height of the *Flags/Static Data* display. Selecting **View** then **Auto Arrange** returns the splitter bar to its original location.

8.2 Setting Programmable bg3055 Options

The bq3055 data flash comes configured per the default settings detailed in the bq3055 data sheet. Ensure that the settings are correctly changed to match the pack and application for the bq3055 solution being evaluated.

IMPORTANT: To get the best performance, it is essential to correctly set these options.

Use the Data Flash Screen to configure the settings.



www.ti.com Operation

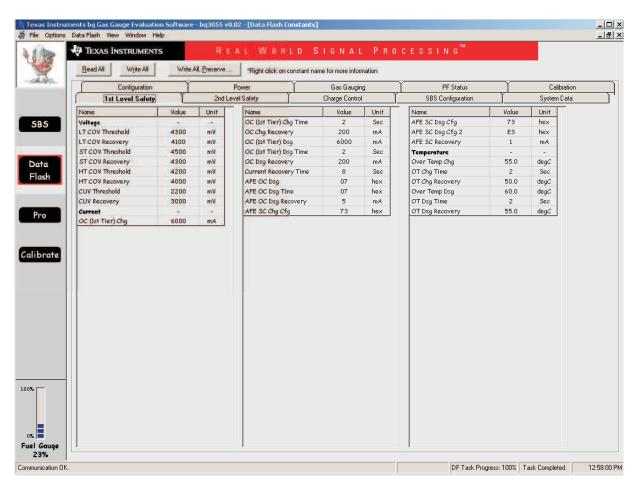


Figure 11. Data Flash Screen, 1st Level Safety Class

To read all the data from the bq3055 data flash, click on menu option | Data Flash | Read All |.

To write to a data flash location, click on the desired location, enter the data, and click **Enter**, which writes the entire tab of flash data, or select menu option | **Data Flash** | **Write All** |. The data flash must be read before any writes are performed to avoid any incorrect data being written to the device.

The | File | Special Export | menu options allows the data flash to be exported.

The data flash configuration can be saved to a file by selecting | **File** | **Export** |, and entering a file name. A data flash file also can be retrieved in this way, imported, and written to the bq3055 using the **Write All** button.

The configuration information of the bq3055 data is held in the data flash.

The bq3055 allows for an automatic data flash export function, similar to the **SBS Data logging** function. This feature, when selected via | **Options** | **Auto Export** |, exports data flash to a sequential series of files named as FilenameNNNNN.gg where N = a decimal number from 0 to 9.

The AutoExport interval is set under the | **Options menu** | with a minimum value of 15 seconds. The AutoExport filename is set under the | **Options menu** |.

When a check is next to | **AutoExport** |, the AutoExport is in progress. The same menu selection is used to turn on/off AutoExport.

If the data flash screen is blank, then the bq3055 that is being used may not be supported by the bqEVSW version that is being used. An upgrade may be required.



Calibration Screen www.ti.com

9 Calibration Screen

9.1 How to Calibrate

The bq3055 must be calibrated using power supplies or a power supply and cell simulation resistors (300 Ω or less) before cells are attached. Before the bq3055 is calibrated:

- Connect and measure a 2-A current source from 1N (–) and Pack (–) to calibrate without using the FETs (calibration using the FETs is not recommended).
- · Measure each cell voltage.
- Measure the temperature of the pack.
- Whether the foregoing steps are necessary depends on the type of calibration being performed.

9.2 To Calibrate the bq3055

To calibrate the bq3055, do the following:

- Select the types of calibration to be performed.
- Enter the measured values for the types selected (except for CC Offset Calibration).
- If Temperature Calibration is selected, select the sensor that is to be calibrated.
- Click the appropriate button to initiate the desired calibration.

9.3 Board Offset Calibration

This performs the offset calibration for the current offset of the board.

Remove any current source, load, or external voltage from the PACK terminals.

Click the Software Board Offset Calibration button.

9.4 Pack Voltage Calibration

This calibrates the voltage at the AFE Pack pin.

Ensure that *Voltage Calibration* has been performed for the pack. If *Voltage Calibration* is not performed, then *Pack Voltage Calibration* calibrates incorrectly.

Remove load/external voltage applied between Pack+ and Pack-.

Click the Pack Voltage button to calibrate.



www.ti.com Calibration Screen

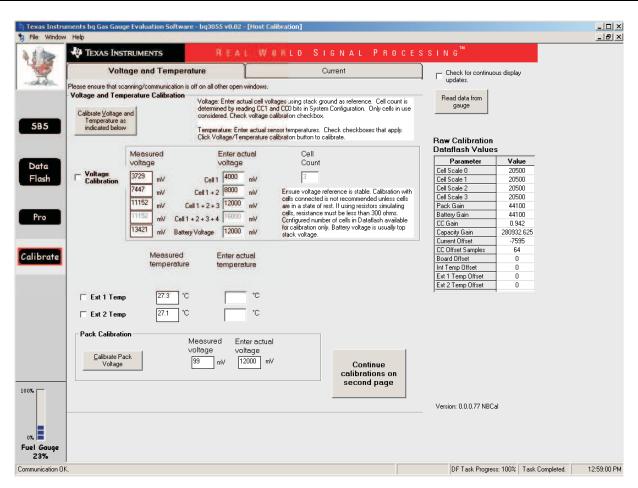


Figure 12. Calibration Screen



Pro (Advanced) Screen www.ti.com

10 Pro (Advanced) Screen

10.1 SMB Communication

The set of read/write operations over SMBus are not specific to any gas gauge. These are provided as general-purpose communication tools.

10.2 Hex/Decimal Converter

The *Hexadecimal Value* and *Decimal Value* boxes convert between hexadecimal (hex) and decimal as soon as values are typed into the boxes. Invalid values can cause erroneous results.

When scaling converted hex values to a higher number of bytes, follow these rules:

- · When *Unsigned* is selected, the left pad contains zeroes.
- When Signed is selected, the left pad contains zeroes for a positive number, or the left pad contains F for negative numbers.

10.3 Reprogramming

To reprogram the device, do the following:

- Ensure that the gauge is in Full Access mode.
- Use the Write SMB Word feature to put the gauge into ROM mode (0x0F00 to cmd 0x00).
- Use the **Srec** programming feature to browse for the desired .srec or .senc file then click the **Program** button to start the transfer.
- Use the SMB Command feature to send 0x08 to execute the program.

If the firmware version was updated, close and re-launch the EVSW to synchronize the tool with the new firmware.



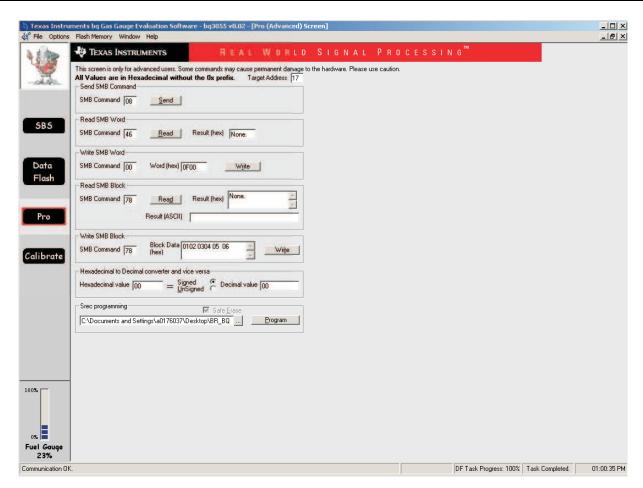


Figure 13. Pro (Advanced) Screen

11 Related Documentation from Texas Instruments

For related documentation, contact the Texas Instruments field representative assigned to work with this device.

Documents:

bq3055 SBS 1.1-Compliant Gas Gauge With Impedance Track™ Data Sheet

bq3055 Technical Reference Manual

Literature Number:

SLUSA91

SLUU440

EVALUATION BOARD/KIT/MODULE (EVM) ADDITIONAL TERMS

Texas Instruments (TI) provides the enclosed Evaluation Board/Kit/Module (EVM) under the following conditions:

The user assumes all responsibility and liability for proper and safe handling of the goods. Further, the user indemnifies TI from all claims arising from the handling or use of the goods.

Should this evaluation board/kit not meet the specifications indicated in the User's Guide, the board/kit may be returned within 30 days from the date of delivery for a full refund. THE FOREGOING LIMITED WARRANTY IS THE EXCLUSIVE WARRANTY MADE BY SELLER TO BUYER AND IS IN LIEU OF ALL OTHER WARRANTIES, EXPRESSED, IMPLIED, OR STATUTORY, INCLUDING ANY WARRANTY OF MERCHANTABILITY OR FITNESS FOR ANY PARTICULAR PURPOSE. EXCEPT TO THE EXTENT OF THE INDEMNITY SET FORTH ABOVE, NEITHER PARTY SHALL BE LIABLE TO THE OTHER FOR ANY INDIRECT, SPECIAL, INCIDENTAL, OR CONSEQUENTIAL DAMAGES.

Please read the User's Guide and, specifically, the Warnings and Restrictions notice in the User's Guide prior to handling the product. This notice contains important safety information about temperatures and voltages. For additional information on TI's environmental and/or safety programs, please visit www.ti.com/esh or contact TI.

No license is granted under any patent right or other intellectual property right of TI covering or relating to any machine, process, or combination in which such TI products or services might be or are used. TI currently deals with a variety of customers for products, and therefore our arrangement with the user is not exclusive. TI assumes no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein.

REGULATORY COMPLIANCE INFORMATION

As noted in the EVM User's Guide and/or EVM itself, this EVM and/or accompanying hardware may or may not be subject to the Federal Communications Commission (FCC) and Industry Canada (IC) rules.

For EVMs **not** subject to the above rules, this evaluation board/kit/module is intended for use for ENGINEERING DEVELOPMENT, DEMONSTRATION OR EVALUATION PURPOSES ONLY and is not considered by TI to be a finished end product fit for general consumer use. It generates, uses, and can radiate radio frequency energy and has not been tested for compliance with the limits of computing devices pursuant to part 15 of FCC or ICES-003 rules, which are designed to provide reasonable protection against radio frequency interference. Operation of the equipment may cause interference with radio communications, in which case the user at his own expense will be required to take whatever measures may be required to correct this interference.

General Statement for EVMs including a radio

User Power/Frequency Use Obligations: This radio is intended for development/professional use only in legally allocated frequency and power limits. Any use of radio frequencies and/or power availability of this EVM and its development application(s) must comply with local laws governing radio spectrum allocation and power limits for this evaluation module. It is the user's sole responsibility to only operate this radio in legally acceptable frequency space and within legally mandated power limitations. Any exceptions to this are strictly prohibited and unauthorized by Texas Instruments unless user has obtained appropriate experimental/development licenses from local regulatory authorities, which is responsibility of user including its acceptable authorization.

For EVMs annotated as FCC - FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant

Caution

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

FCC Interference Statement for Class A EVM devices

This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

FCC Interference Statement for Class B EVM devices

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- · Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- · Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

For EVMs annotated as IC - INDUSTRY CANADA Compliant

This Class A or B digital apparatus complies with Canadian ICES-003.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

Concerning EVMs including radio transmitters

This device complies with Industry Canada licence-exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Concerning EVMs including detachable antennas

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication.

This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Cet appareil numérique de la classe A ou B est conforme à la norme NMB-003 du Canada.

Les changements ou les modifications pas expressément approuvés par la partie responsable de la conformité ont pu vider l'autorité de l'utilisateur pour actionner l'équipement.

Concernant les EVMs avec appareils radio

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes : (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Concernant les EVMs avec antennes détachables

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante.

Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

[Important Notice for Users of this Product in Japan]

This development kit is NOT certified as Confirming to Technical Regulations of Radio Law of Japan

If you use this product in Japan, you are required by Radio Law of Japan to follow the instructions below with respect to this product:

- Use this product in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry's Rule for Enforcement of Radio Law of Japan,
- 2. Use this product only after you obtained the license of Test Radio Station as provided in Radio Law of Japan with respect to this product, or
- 3. Use of this product only after you obtained the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to this product. Also, please do not transfer this product, unless you give the same notice above to the transferee. Please note that if you could not follow the instructions above, you will be subject to penalties of Radio Law of Japan.

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EVALUATION BOARD/KIT/MODULE (EVM) WARNINGS, RESTRICTIONS AND DISCLAIMERS

For Feasibility Evaluation Only, in Laboratory/Development Environments. Unless otherwise indicated, this EVM is not a finished electrical equipment and not intended for consumer use. It is intended solely for use for preliminary feasibility evaluation in laboratory/development environments by technically qualified electronics experts who are familiar with the dangers and application risks associated with handling electrical mechanical components, systems and subsystems. It should not be used as all or part of a finished end product

Your Sole Responsibility and Risk. You acknowledge, represent and agree that:

- 1. You have unique knowledge concerning Federal, State and local regulatory requirements (including but not limited to Food and Drug Administration regulations, if applicable) which relate to your products and which relate to your use (and/or that of your employees, affiliates, contractors or designees) of the EVM for evaluation, testing and other purposes.
- 2. You have full and exclusive responsibility to assure the safety and compliance of your products with all such laws and other applicable regulatory requirements, and also to assure the safety of any activities to be conducted by you and/or your employees, affiliates, contractors or designees, using the EVM. Further, you are responsible to assure that any interfaces (electronic and/or mechanical) between the EVM and any human body are designed with suitable isolation and means to safely limit accessible leakage currents to minimize the risk of electrical shock hazard.
- 3. You will employ reasonable safeguards to ensure that your use of the EVM will not result in any property damage, injury or death, even if the EVM should fail to perform as described or expected.
- 4. You will take care of proper disposal and recycling of the EVM's electronic components and packing materials.

Certain Instructions. It is important to operate this EVM within TI's recommended specifications and environmental considerations per the user guidelines. Exceeding the specified EVM ratings (including but not limited to input and output voltage, current, power, and environmental ranges) may cause property damage, personal injury or death. If there are questions concerning these ratings please contact a TI field representative prior to connecting interface electronics including input power and intended loads. Any loads applied outside of the specified output range may result in unintended and/or inaccurate operation and/or possible permanent damage to the EVM and/or interface electronics. Please consult the EVM User's Guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative. During normal operation, some circuit components may have case temperatures greater than 60°C as long as the input and output are maintained at a normal ambient operating temperature. These components include but are not limited to linear regulators, switching transistors, pass transistors, and current sense resistors which can be identified using the EVM schematic located in the EVM User's Guide. When placing measurement probes near these devices during normal operation, please be aware that these devices may be very warm to the touch. As with all electronic evaluation tools, only qualified personnel knowledgeable in electronic measurement and diagnostics normally found in development environments should use these EVMs.

Agreement to Defend, Indemnify and Hold Harmless. You agree to defend, indemnify and hold TI, its licensors and their representatives harmless from and against any and all claims, damages, losses, expenses, costs and liabilities (collectively, "Claims") arising out of or in connection with any use of the EVM that is not in accordance with the terms of the agreement. This obligation shall apply whether Claims arise under law of tort or contract or any other legal theory, and even if the EVM fails to perform as described or expected.

Safety-Critical or Life-Critical Applications. If you intend to evaluate the components for possible use in safety critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, such as devices which are classified as FDA Class III or similar classification, then you must specifically notify TI of such intent and enter into a separate Assurance and Indemnity Agreement.

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